



New York Monitor

Advancing Technology for Humanity

A PUBLICATION OF THE IEEE NEW YORK SECTION

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ADD-SPECIAL

IEEE NY MONITOR

A PUBLICATION OF THE IEEE NEW YORK SECTION

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	Treasurer	Simon Odie
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NY Monitor

April 2016 - ADD Special

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Read the NY Monitor

It is your news that we publish here

Contribute to the Monitor

QUICK DATE CHECKS FOR YOUR CALENDAR

Dates for the 2016 Executive Committee meetings at IEEE NY Section

~~10 January~~

~~10 February~~

~~9 March~~

~~13 April~~

11 May

8 June

No meetings during the months of July and August

14 September

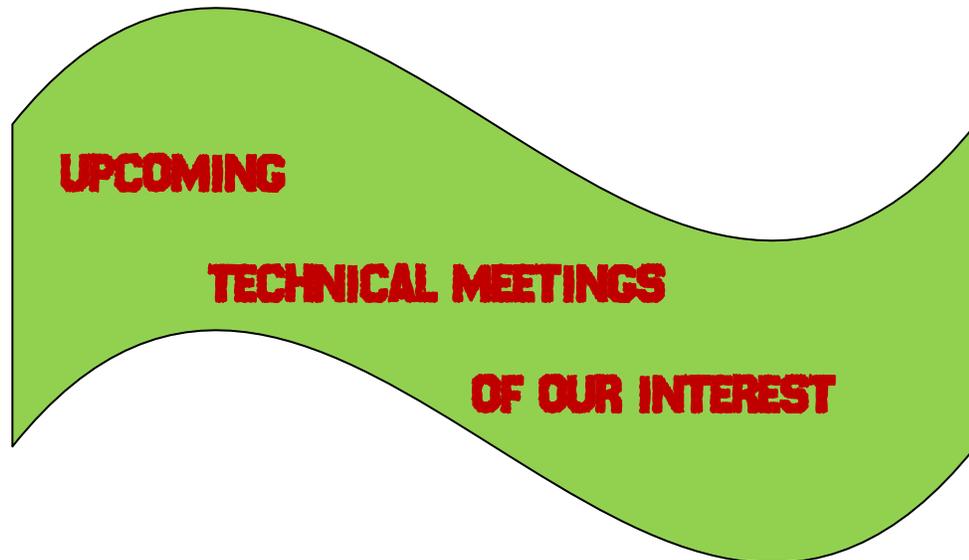
12 October

9 November

14 December

Unless otherwise notified all ExComm meetings are scheduled for 12:30 pm at the ConEd Building, 4 Irving Place, New York. All members of the New York Section are invited to participate in the ExComm meetings.

However, for reasons of security, to attend such meetings you must give advance notice to the Section chair.



**UPCOMING
TECHNICAL MEETINGS
OF OUR INTEREST**

(For further details on each event please see the individual notices at the end of this posting)

- **28 April, Thursday, 5.00pm – 7.0pm**, ConEd Building, New York: PES/IAS New York Chapter presentation: **Key Convergences in the Global Electrical Industry**. This event is free to all (IEEE members, guests and members of our community. However, for reasons of security, RSVP is required.
- **28 April, Thursday, 6.30pm – 8.0pm**, German House, 871 United Nations Plaza (First Avenue with 49th Street), a German Universities Alliance UA7, presentation: **Bridging the U.S. Skills Gap - A Transatlantic Discussion on Vocational Training and Best Practices**
- **30 April, Saturday, Whole day**: White Plains High School, 550 North Street, White Plains, NY, Tri County Science and Technology Fair, Science fair for the entire family, especially the children. The IEEE is firm supporter of the non-for-profit Fair. For further information please visit <http://discoverctr.org>



LOOKING FAR AHEAD

- 23 September, Long Island University, Brooklyn Campus: 2nd 2016 SPAC/iSTEP conference in New York. Details will be available in June edition of this newsletter
- **1-3 December, Thursday through Saturday**: Women in Engineering (WIE) Forum **on Inspiring and Empowering Women in Technology**, Boston, MA. For more information please write to 44griffin@comcast.net



This month we celebrated our annual Award Dance Dinner ceremony at which we honored the six new IEEE Fellows and five distinguished volunteer members of the New York Section who devoted their time energy to the uphold the lofty ideals of the IEEE. This year we had a very good turnout. Credit goes to David Horn, the chair of the special events committee at the New York Section. David was also the master of the ceremony. He was helped by Wilson Milian, the Section chair.

Every year at the ADD I always look forward to the cocktail hour before the main ceremony commences. The eats and drinks are superb and this year was no exception. This cocktail hour is also ideal for mingling with old and present colleagues in an informal ambience, and an opportunity to meet many others from our respective profession. The food (filet mignon for me!) was good and the atmosphere jolly! You will find a report on the ceremony inside this edition of the NY Monitor. You will also find links to photographs taken there in Power Point format (and later converted into pdf). In a

couple of files you will notice the captions. However, for the third file we could not place *all* of the names spelled correctly. Hence, instead of having some photos with names and others without we decided to omit the names altogether. We would kindly request you to send the names of the persons you recognize to me (a.dutta-roy@ieee.org) with the number/s of the slide/s in which they appear. We'll thus complete the file of those photos and publish them again for your pleasure and posterity. We thank Kai Chen, Bill Coyne and Jalal Gohari for sharing the photos with us.

Even besides the award ceremony we have had an eventful month. Wherever possible, we have posted the reports. We know that all of you are busy with your professional work and may not be able to write description of the events. But please try to find someone who can help us to make the Monitor an exemplary newsletter in the entire realm of the IEEE.

Enjoy reading the NY Monitor!



AWARD DINNER DANCE 2016

Finally, the evening that most members of the IEEE New York Section had been expecting arrived! The annual gala of the award dinner dance (ADD) was celebrated on 16 April at Hilton Midtown Hotel in the heart of Manhattan. Thanks to the change of dates and the balmy spring weather, the number of attendees surpassed that of the past years.

At this event we introduced and honored the members whose memberships were upgraded to that of Fellows. Some of our readers may not know the principles behind the upgrade. This upgrade process has been in place since the merger of the Institute of Radio Engineers (IRE) and the American Institute of Electrical Engineers

(AIEE). As per the IEEE rules, in any one given year, only one-tenth of one percent of the total voting membership can be elevated Fellow grade for their technology-related achievements. You can imagine the honor associated with the term Fellow. In 2014 to commemorate 50 years of elevating members to Fellow grade the IEEE even minted some special coins. In the following pages you will find the names of the 2016 Fellows from the New York Section. Mr Wilson Milian, the chair of the NY Section called upon Dr Amitava Dutta-Roy, a Life Fellow to present the Fellow certificates to those elevated to the highest grade of membership this year. Also present in the presentation ceremony was Stefano Galli, another IEEE Fellow.



IEEE Fellow coins minted in 2014 to commemorate 50 years of the initiation of Fellow program



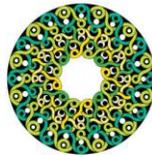
A the ADD ceremony w also proudly honored our volunteer awardees for their engineering accomplishments and dedication to the advance of technology and to the IEEE. David Horn and Wilson Milian presented the Region 1 awards as well as the Friend of the IEEE award to ConEd; Ky Fu, Larry Scarcia and Muamer Dedovic presented the VTS Engineer of the Year award; and Ajoy Das

and Tom Villani presented the PES Award to Arnold Wong. The award citations may be seen on the following pages.

Please click on the name to see the photos taken by: [Kai Chen](#) (Fellows and Awardees), [Bill Coyne](#) and Jalal Gohari (general), and [Thomas Villani](#) (also general)

New IEEE Fellows and the Region 1 awardees in the New York Section

The IEEE NY Monitor congratulates all 2016 IEEE Fellows



HUI LEI

IBM T. J. Watson Research Center:

For contributions to scalable and dependable data access in distributed computing systems

YIXIN DIAO

IBM T. J. Watson Research Center:

For contributions to modeling, optimization, and control of computing systems

VISHAL MISRA Columbia University: *For contributions to network traffic modeling, congestion control and Internet economics*

SUNDEEP RANGAN

NYU Polytechnic School of Eng.:

For contributions to orthogonal frequency division multiple access cellular communication systems

IVAN SELESNICK

NYU Polytechnic School of Eng.:

For contributions to wavelet and sparsity based signal processing

MEHMET SOYUER IBM Thomas J. Watson Research Center: *For contributions to the design of high-frequency integrated circuits for clocking and communications*



2016 IEEE Region 1 Awardees in New York Section

FRANK STANTON

Daidone Electric, Inc.

An IEEE Region 1 award for Technological Innovation
(Industry / Government)

*For exemplary contributions to electrical engineering
industry in the design and implementation of vital
electronic systems and infrastructure for the public's
benefit*

*For outstanding leadership and contributions to
communication systems engineering management in
the design and construction of Railroad communication
and Passenger information systems for the MTA New
York City Transit*

ROBERT GOMEZ

MTA New York City Transit:

An IEEE Region 1 award for Managerial Excellence in an
Engineering Organization

*For outstanding leadership and contributions to
electrical engineering management in the design and
construction of vital railroad signaling capital
infrastructure works for the MTA New York City
Transit Subway system*

RAFAEL RUFFO

MTA New York City Transit:

An IEEE Region 1 award for Managerial Excellence in an
Engineering Organization

2016 IEEE PES Society Award

ARNOLD WONG

Con Edison

Outstanding Engineer



MANY TECHNOLOGY COMPANIES HAVE SUPPORTED THE IEEE NEW YORK. WE ARE THANKFUL TO ALL OF THEM BOTH AND HOPE THEY WILL CONTINUE WITH THEIR COOPERATION

BUILDING EXPECTATIONS



Moving Transit Systems Ahead

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With a complete systems solution, we deliver design support, construction engineering, project management, installation, testing, start-up and maintenance services.

We can get you there. We're building transit systems for tomorrow.

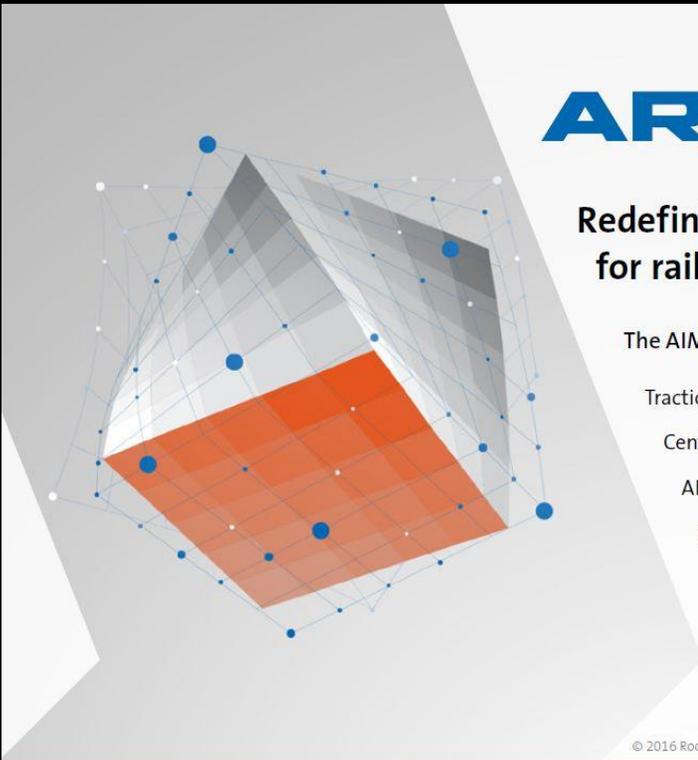
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THE NEW FACE OF THE IEEE COMMUNICATIONS SOCIETY NEW YORK CHAPTER KICKS OFF WITH A PRESENTATION AT COLUMBIA

Bonnie Tran, Richard Sam and Warner Sharkey



Warner Sharkey, the chair of the ComSoc NY chapter greets the attendees

On 30 March last the IEEE ComSoc NY Chapter kicked off its 2016 theme *Communications Engineering for Embedded Systems* at Columbia University, New York with a presentation on Voice over Bluetooth Low Energy (BLE) and microelectromechanical systems or MEMs-based directional microphones. The 2016 volunteer leaders* of ComSoc NY chapter invited Mr Tom Hopkins, a STM Technical Fellow and Dr. Mateo Fusi also of STM. –who has been with STM for 35 years as an applications engineering manager- and Manager of IoT Systems, –who is operating in the East AME Region (East Coast USA and Canada) for STM.



Dr. Mateo Fusi and Tom Hopkins prepare their presentations and demos

A few words on ST Microelectronics (STM), a Italo-French company headquartered in Geneva, Switzerland: it is a leading semiconductor company and is among the largest in the world. The first letter “S” in its name comes from the Italian firm Società Generale Semiconduttori and the letter “T” came from the French company Thomson Semiconducteurs (more famously just Thomson). Their spectrum of hardware and software products support advanced connected solutions in industry sectors such as automotive, energy and IoT. With such impressive offerings the company is now in the market of wearable technology and part of their portfolio is the STM32Cube, a comprehensive software tool that significantly reduces

development efforts, time, and the cost. With a wide range of free libraries, users can indulge in a variety of projects.

The BLUEVOICELINK1, an expansion software package for STM32Cube, runs on the STM32 ARM. It includes drivers and middleware for Bluetooth Low Energy (BlueNRG) and MP34DT01-M digital MEMS microphones. The expansion is built upon the STM32Cube software technology that offers portability across different STM32 microcontrollers. The software comes with examples of implementation of the drivers for X-NUCLEO-IDB04A1 and X-NUCLEO-CCA02M1 when both are connected to a NUCLEO-F401RE.

The NUCLEO-F401RE is an STM32 Nucleo board. It enables users to build prototypes with any STM32 microcontroller line. During the session,



Mateo Fusi, Manager at STM, presenting Voice over Bluetooth Low Energy.

Mateo and Tom used the NUCLEO-F401RE board along with MEMS microphones and BLE modules to demonstrate the transmission of Voice over BLE and the beam-steering capability of their microphone software.

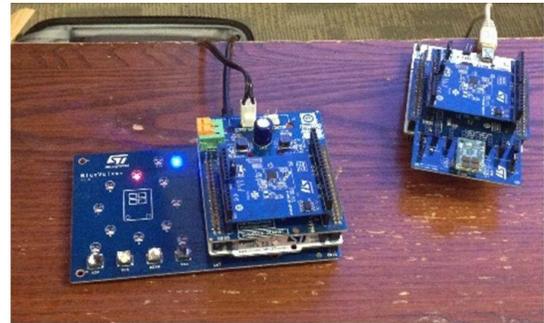
As part of the demos, Tom spoke into a MEMS microphone module and his audio drove the speakers placed on the other side of the table. Then he turned the microphone 90 degrees and showed that the speakers turned silent. This demonstrated that, although the microphones captured his voice regardless of the angle, the beam-steering software

filtered the voice signals based on the directions they came from.

Another demo illustrated the Voice over BLE capability. To do so, they set up Bluetooth connection between a smartphone and one of their sensor modules. As Mateo spoke into the module, equipped with a microphone, his voice commands to the smart phone, running voice recognition software, controlled music audio.

As the session ended, more than half of the thirty-three students who attended received two sets of

ARM processor boards along with the Bluetooth and Microphone MEMS boards for their own use and learning, courtesy of STM. And as more companies enter the realm of IoT and open-source



Two NUCLEO-F401RE ARM processor boards with MEMS expansion boards stacked on top of each

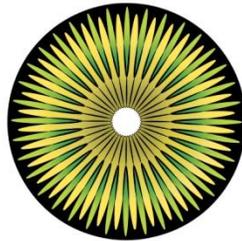
software and hardware, tinkers and innovators will have an ever-increasing array of tools to choose from.

Tom Hopkins who has been with STM for 35 years and is now an applications engineering manager. Dr. Mateo Fusi is a manager of the IoT Systems and is in charge of STM's operations in the East AME Region (East Coast USA and Canada) of STM.

*The 2016 officers of the ComSoc NY chapter are:
Chair: Warner Sharkey - cruisingsailor@ieee.org
Vice-Chair: Richard Sam - richard.s.sam@ieee.org
Secretary: Praveenkumar Khethavath - pkhethavath@lagcc.cuny.edu
Interim Treasurer/WIE and Student Coordinator: Bonnie Tran - bt2389@columbia.edu
ComSoc NY Web Site: <http://ny.chapters.comsoc.org/>



Warner Sharkey, P.E., ComSoc NY Chairman- presenting a Certificate of Appreciation to Tom Hopkins (left) and Mateo Fusi (right)



IEEE NY CHAPTER LENDS SUPPORT TO “BE AN ENGINEER” INITIATIVE

AT THE HUDSON VALLEY ENGINEERING EXPO

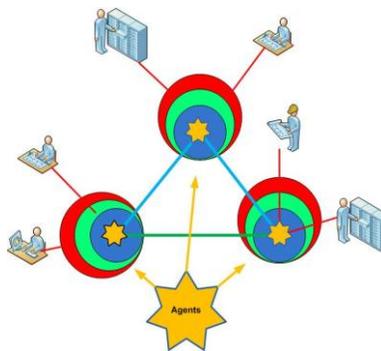
On 3 April the Tappan Zee subsection of the IEEE New York participated in the Hudson Valley Engineering Expo where the annual “Be an Engineer” program was realized at the White Plains High School Gymnasium. The objective of the initiative is to motivate the young minds to take up engineering as their profession. Many school children and their parents visited the expo. Robert

Pellegrino, chair of the Tappan Zee subsection was at hand to explain first-hand the excitement engineering brings to us and how the future engineers can benefit our society. Pellegrino reports that a considerable number of children and their parents stopped at the IEEE booth and asked questions. Thank you, Robert!



Robert Pellegrino at the IEEE booth, Hudson Valley Engineering Expo

AGENT-BASED COLLABORATIVE TECHNOLOGIES AND SYSTEMS
SMC NY CHAPTER AND EDUCATION COMMITTEE PRESENTATION



The Systems, Man and Cybernetics (SMC) chapter and the Education Committee jointly are one of the most active groups in the IEEE NY Section. Their latest April offering was a presentation on Agent-Based Collaborative Technologies and Systems. It

was given by Dr Weiming Shen, Senior Research Scientist with the National Research Council Canada and Adjunct Professor at the University of Western Ontario and McMaster Universities, and a Distinguished Lecturer of the IEEE SMC Society.

Intelligent systems, wherever they may be, are getting exceedingly complex. Imagine an apartment complex where each unit is equipped with multiple sensors; smoke-CO detector, thermostats, security alarms and garage door openers etc. A more sophisticated system could also provide individual temperature and light control in every room in every unit. The emerging IoT technologies are also about to enter your home or apartment. For most efficient operation inside an apartment block all these single subsystems must be connected together and then linked to the utilities, and fire departments etc. In such a complex system an agent can be defined as a software system that communicates and cooperates with each individual subsystem and other systems to solve a complex problem that is beyond the

capability of each constituent unit. Intelligent software agents also can be used to encapsulate existing software systems to realize legacy systems integration, represent manufacturing resources (e.g., operators, machines, robots, and cells) to implement distributed manufacturing process planning, scheduling and execution control, and to represent organizations to facilitate collaboration, coordination, and negotiation. Dr Shen has vast experience in this field. He has successfully designed agent-based systems in Canada. Savings in utility bills have been noticeable. After his presentation Dr Shen was inundated with questions. The Monitor, once again, congratulates SMC chapter for their continuation with dissemination of information on latest in IT.



Anticlockwise: Dr Weiming Shen, the speaker; Dr Amitava Dutta-Roy, editor of the NY Monitor; Dr Ping-Tsai Chung, chair, SMC NY Chapter; a group photo; Dr Shen receives a certificate of appreciation from the SMC NY chapter chair, Dr Chung, Prof at LIU,

iSTEP/SPAC Conference

IEEE is dedicated to promote education of young students who have the potential to become engineers. To promote such consciousness among the younger set the IEEE Region 1 has been promoting conferences. One of them is known as Student Professional Awareness Conference (SPAC) and the other is Integrated Students Transition to Engineering/Technology Professional (SPAC). They provide students, industry professionals, and the IEEE leaders the opportunity to share their career experiences at one single venue. More experienced professionals talk on how young persons can shape

their future and provide career development tools necessary for succeeding in engineering. In Region 1 often both conferences are combined where a large number of professional engineers and teachers can mingle with the students and motivate them to take up engineering and stick to the profession. This year the first iSTEP/SPAC conference in New York was held at New York Institute of Technology (NYIT) on 1 April and was attended by almost 40 students. The credit goes to our Robert Pellegrino for coordinating the meetings and panel discussions.



Student attendees at the iSTEP/SPAC Conference at NYIT, 1 April. 2016



IEEE Professional volunteers to inspire the students: Kim Smith, Warner Sharkey, Wilson Milian and Arnold Wong at iSTEP/SPAC at NYIT

FUNDING POSSIBILITIES



Present trends in most research and development work call for collaborative efforts that may be undertaken within only one country or, thanks to the rapid communications through the Internet, can span different nations across the world. One common problem to both alternatives is obtaining adequate *funds* to support the work! Those who have tried to get funding for their research know about the problem all too well. In the following you will read about a source of funding for research work that attract researchers living in European Union and other countries though here we are interested mostly in collaboration between the EU and the USA.

Recently, I attended a presentation at the German Center for Research and Innovation (GCRI) in New York City. The theme was cross-Atlantic collaboration in science and technology research. The scientifically minded leaders on both sides of the Atlantic understand the funding problem. The EU has taken a positive step to ease the problem somewhat. The following has been adapted from the press release on a project known as Horizon 2020 spearheaded by EU countries.

EU – USA Research Collaboration and Funding Opportunities in Horizon 2020, the European Framework Program for Research and Innovation Discovering solutions to societal challenges requires a strong global knowledge economy. On Thursday, March 10, renowned policy experts and researchers convened at the German Center for Research and Innovation (GERI) in New York to discuss the European Union’s largest research and innovation initiative. With nearly €80 billion in funding allocated for over seven years, Horizon 2020 is the EU’s largest research and innovation

initiative. By taking great ideas from the lab to the market, this program promises many breakthroughs, which are intended to enhance Europe’s global competitiveness. Established as a means of driving economic growth and creating jobs, Horizon 2020 will make it easier for public and private sectors to work together to push the frontiers of innovation. The program focuses on three overarching priorities: excellent science, industrial leadership, and solutions to global challenges. **Horizon 2020 is open to participants from anywhere in the world as the program recognizes the growing importance of internationalizing how knowledge is produced and used.** Panelists from both sides of the Atlantic at the German Center for Research and Innovation (GCRI) in New York elaborated the different types of international cooperation that Horizon 2020 supports. The presentations addressed in detail the main elements of Horizon 2020 with regards to content, types of activities funded, forms of participation, and application procedures. Dr. Joann Halpern, Director of the German Center for Research and Innovation in New York, spoke about the work of the GCRI and various funding opportunities in Germany. Dr. James P. Gavigan, Minister Counselor and Head of the Science, Technology, and Innovation Section of the Delegation of the European Union to the USA gave an overview of the Horizon 2020 program. In particular, he explained the cases where US-based participants can or might qualify to receive E.U. funding to cover the cost of their participation in selected Horizon 2020 projects. He also described how Horizon 2020 accommodates international cooperation at the individual researcher, collaborative project, or program/agency level.

Interested in funding through Horizon 2020? Find out the opportunities by visiting:

<https://ec.europa.eu/programmes/horizon2020/>

#####

You may be interested to know

How Can We Make the **Internet of Things the Innovation of Things**? A 35-min video explain and answers many questions: Moderator: Joshua New, Policy Analyst, Center for Data Innovation; speakers: Travis Hall, Telecommunications Policy Analyst, National

Telecommunications and Information; Karen Rose, Senior Director, Strategy & Analysis, Internet Society; and Juan Carlos Zuñiga, Principal Engineer, InterDigital; <https://livestream.com/internetsociety/sotnw/videos/120095892>

IoT, Engineering and the government regulations

Any kind of engineering has its business and social implications. Thus, a product or a service must go through a series of checks and balances: standardization, competition, consumer acceptance, health hazards, and federal laws and international regulations. In case of the Internet of Things they become most important, since IoT is being designed to affect all (at least a big chunk of human population). Thus, it is no longer enough to invent a gadget and then hope for the best that it will have a market. The following questions come to mind (forwarded by Joly Macfie of the Internet Society):

- “We hear that IoT will change the world. We also hear that it’s overhyped. To what extent do you believe IoT will drive major economic/technological change? In what

ways do you think it will have the greatest or the least impact?

- What fosters innovation in this area? What inhibits innovation? How can diplomatic engagement best be employed to foster innovation?
- Interoperability is often viewed as central to achieving IoT’s full potential. Do you see solutions/approaches emerging? Is there pressure to converge on a solution prematurely? A range of standards organizations and consortia are working on IoT-related standardization. Is standardization happening too slowly, too quickly, or at the right speed? Are there preferred forms or processes for achieving beneficial standardization? What role, if any, is there for international regulation?
- How will the radio frequency spectrum play a role in supporting IoT uptake? What are

the best approaches for achieving ample and harmonized spectrum to support this growth?

- How do the many international/governmental/regional initiatives promoting IoT/Smart Cities affect your economic outlook?
- What do you see as the most significant challenges associated with privacy concerns about open and proprietary IoT data analytics? Where and how should these be addressed?
- What do you see as the most significant security, reliability, and public safety challenges associated with IoT applications and services?
- Given that that IoT products and services reach beyond the IT sector, what are the

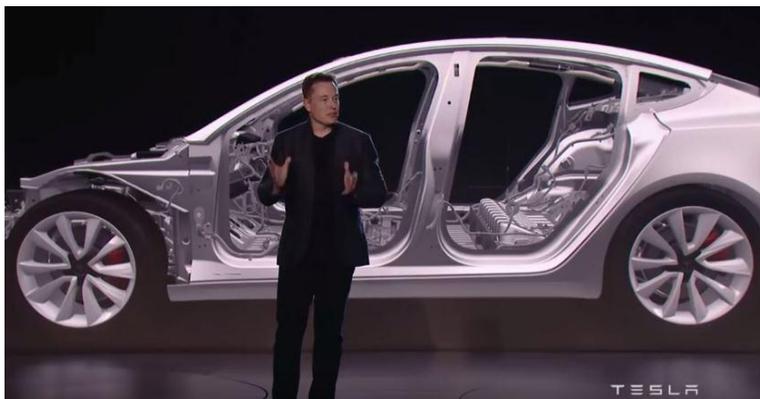
challenges and opportunities you see in working with international partners and customers from other sectors (e.g., agriculture, healthcare, utilities, etc.) on IoT and Smart Cities issues?

- Is the work of the ITU-T's SG20 on Internet of Things and Smart Cities and Communities relevant to your own work in these areas?"

View the following Web site for some of the answers:

<https://www.federalregister.gov/articles/2016/03/17/2016-06049/notice-of-meeting-of-the-international-telecommunication-advisory-committee>

HEY, MISTER, HAVE SOME CHANGE?
WANT TO BUY MY TESLA 3?



Elon Musk and his TESLA Model 3

For the full video visit <https://www.youtube.com/watch?v=wqMJeR1Yvm4>



POWER & ENERGY SOCIETY
INDUSTRY APPLICATIONS SOCIETY
NEW YORK SECTION



You are invited to a meeting of the PES & IAS NY Chapter on:

Thursday April 28, 2016

Key Convergences in the Global Electrical Industry

THE PRESENTATION:

This presentation will discuss Key Convergences in the Global Electrical Industry including worldwide interconnected AC system challenges. Projects associated with China's "West-to-East Power Transmission Drive", Europe's "Supergrid" and in South America will be presented. With the Global Electrical Industry projected to be a \$120 Billion market by 2020, new smart grid technologies will need to be developed to manage the grid as well as to manage and optimize the light speed business aspects of the new grid.

THE PRESENTER:



Phillip G. Harris founded and is presently the Chairman, CEO and President of Tres Amigas, LLC. Tres Amigas is the interconnection project that will eventually link the three largest North American grids. Prior to Tres Amigas, Mr. Harris was Chair, President and CEO of PJM from 1992 to 2007. Under his leadership, PJM became the largest competitive wholesale electricity market. Mr. Harris has served as a member of the North American Electric Reliability Council (NERC) Board of Trustees, is a member of the National Association of Corporate Directors. Mr. Harris has received numerous industry awards including CEO of the Year 2005, Platts Global Energy Awards, James H McGraw 1999 for business excellence, Computerworld Smithsonian Award for Technical Innovation. In 2016 Mr. Harris was named by the Public Utilities Fortnightly as one of the top twenty individuals who was the most influential in the electric industry since 1990. Mr. Harris is a graduate of the US Military Academy at West Point, earned

the MA in Business Management from U Northern Colorado, and is a Certified Management Accountant, a Computer Systems Professional and member of IEEE.

ALL ARE INVITED – PLEASE POST

RSVP: <https://meetings.vtools.ieee.org/m/39309>

Chair Programs: Arnold Wong

wongar@coned.com or (212) 460-4189

Chair Technical Committee: Sukumar Alampur, PE

salampur100@hotmail.com or (917) 522-2844

FOR SECURITY REASONS: NO WALK-INS!

When: 5:00 pm — Starts-Refreshments & Program

7:00 pm — Program Ends

Where:

Con Edison

Edison Room, 19th Floor

4 Irving Place, New York, NY 10003

Nearest Subway: 14th St/Union Sq.

This program will be awarded IEEE Continuing Education Units.

THE INSTITUTE OF ELECTRICAL AND ELECTRONICS ENGINEERS, INC.



The German Consulate General New York and UAS7 cordially invite you to a panel discussion on



Consulate General
of the Federal Republic of Germany
New York



Bridging the U.S. Skills Gap - A Transatlantic Discussion on Vocational Training and Best Practices

Thursday, April 28, 2016 from 6:30 p.m. – 8:30 p.m.

Panelists:

◆ Dr. Christine Benz, Training Manager, Trumpf, Inc.

◆ Dr. Robin Mishra
Head of Science and Technology at German Embassy Washington, D.C.

◆ Prof. Dr. Bernd Reisert
Professor of Political Science (Labor Market and Education Policy), former President of the Berlin School of Economics and Law and Chairman of UAS7

◆ Dr. Gale Tenen Spak
Associate Vice President of Continuing and Distance Education at
New Jersey Institute of Technology

Moderator:

◆ Dr. Joann Halpern
Director of the German Center for Research and Innovation New York City

German House, 871 United Nations Plaza (First Ave. at 49th Street), New York, NY

Please register at <https://skillsgapbridge.eventbrite.com> Password: **Skills Gap**

Seating is limited. Reception to follow.

While most countries around the world have seen an unprecedented expansion of their education and skill base over the past decades, a persistent gap still exists between the kind of knowledge and skills that are most in demand in the workplace and those that education and training systems continue to provide. In this environment, the German dual system of vocational training is increasingly seen as a major contributor to narrowing the skills gap. While this gap affects the entire U.S. workforce, it has a particularly strong impact on the American manufacturing sector, where many jobs remain unfilled because the potential workforce lacks requisite skills. This is why U.S. industries and manufacturers have increasingly implemented vocational training opportunities, which provide a combination of on-the-job training and classroom learning and offer young people certified career paths as an alternative option to university education. In Germany, the dual system of vocational training has long been successful and has especially benefited the country's smaller and mid-sized companies. Can similar vocational training systems successfully be implemented in the U.S., and how can the German vocational training model influence this process? Who are the main stakeholders from government, industry and higher education responsible for setting up successful vocational training programs in the U.S. and in Germany, and what can they

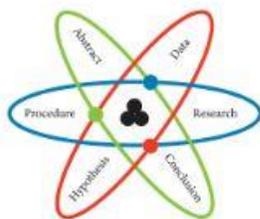
report about major challenges and best practices? We invite you to join us for a transatlantic discussion on the current state and future of U.S. workforce development.



The Putnam Children's Discovery Center

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Tri County Science and Technology Fair



...is pleased to welcome Pepsi Global R&D
as Grand Sponsor 2016



PEPSICO

Global R+D

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